

LIQUID RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

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ABSTRACT

According to the invention, a liquid resin composition which has favorable wet spreadability after mounting of a chip and exhibits excellent solder cracking resistance even in a high-temperature solder reflow process at about 260°C, i.e., even when being
10 used in lead-free solder, and a semiconductor package using the liquid resin composition are provided. In the liquid resin composition of the invention, an acrylic copolymer having a radical polymerizable functional group contains alkyl (meth)acrylate as a constituent monomer having a linear or branched alkyl group having 6 to 9 carbon atoms in an amount of 10 wt% to 40 wt% of the entire constituent monomers.